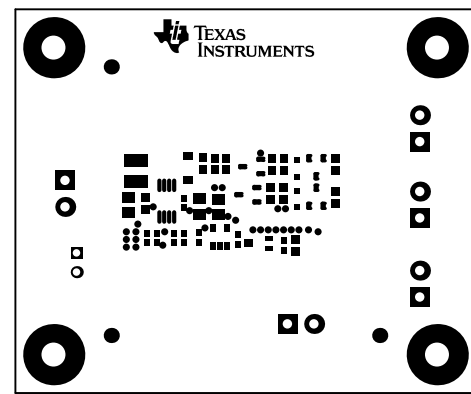
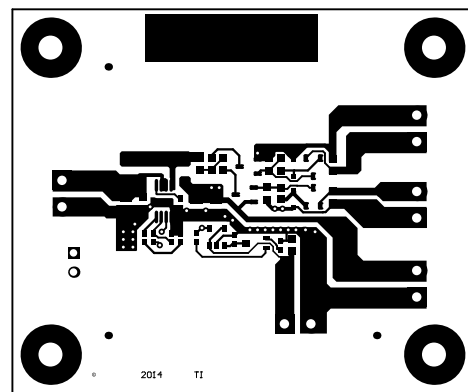


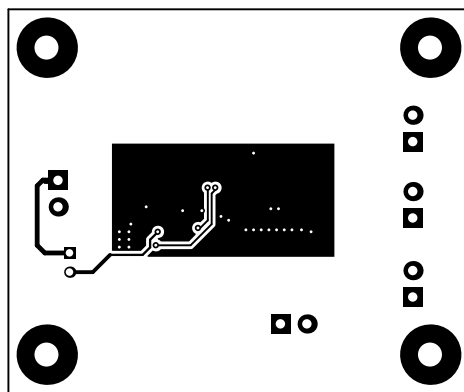
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	PMP9770	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME =	Top Overlay					
PLOT NAME =	GENERATED 1		12-29-2014		5:04:16 PM	
						TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	PIP9770	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME =	Top Solder					
PLOT NAME =	Top Solder Mask		GENERATED :	12-29-2014	5:04:17 PM	TEXAS INSTRUMENTS

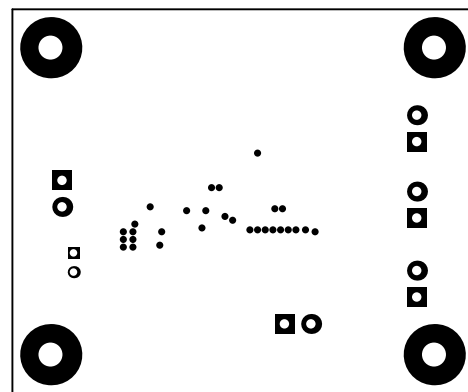


ALL artwork VIEWED FROM TOP SIDE	BOARD #:	PPD9770	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME =	Top Layer					
PLOT NAME =	GENERATED 1		12-29-2014		5:04:17 PM	
TEXAS INSTRUMENTS						



Not In VersionControl

ALL artwork VIEWED FROM TOP SIDE	BOARD #:	PH9770	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME =	Bottom Layer					
PLOT NAME =	GENERATED	1	12-29-2014	5:04:18 PM	TEXAS INSTRUMENTS	

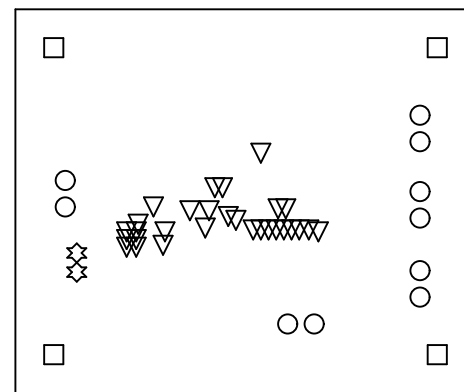


ALL ARTWORK VIEWED FROM TOP SIDE	BOMID #: P1P9770	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED: 1	12-29-2014	5:04:19 PM
			TEXAS INSTRUMENTS

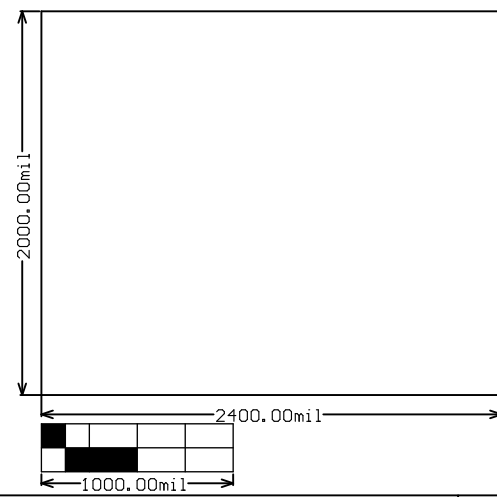


ALL ARTWORK VIEWED FROM TOP SIDE	BORD #: P199770	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED 1 12-29-2014 5:04:20 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Material	Hole Type
▽	1	0.0000 (0.0000mm)	21X	Count
●	1	0.0000 (0.0000mm)	21X	Count
○	1	0.0000 (0.0000mm)	21X	Count
□	1	0.0000 (0.0000mm)	21X	Count
Total				



ALL ARTWORK VIEWED FROM TOP SIDE	BOMRD #:	PH99770	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME =	Drill Drawing					
PLOT NAME =	GENERATED :	12-29-2014	5:04:21 PM	TEXAS INSTRUMENTS		



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	PH99770	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME =	N2 Board Dimensions					
PLOT NAME =	Board Dimensions	GENERATED :	12-29-2014	5:04:21 PM	TEXAS INSTRUMENTS	

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